- Eight Latches in a Single Package
- 3-State Bus-Driving Inverting Outputs
- Full Parallel Access for Loading
- Buffered Control Inputs
- pnp Inputs Reduce dc Loading on Data Lines
- Package Options Include Plastic Small-Outline (DW) Packages and Standard Plastic (N) 300-mil DIPs

#### OE V<sub>C</sub>C 1Q **∏** 2 19 8Q 1D **∏** 3 18 N 8D 2D ∏ 17**∏** 7D 2<mark>0</mark> 5 16 7 7Q 3Q [ 15 6Q 3D [ 14 **1** 6D 4D Π 13**∏** 5D 4Q [ 12 1 5Q GND [] 11 🛮 LE

DW OR N PACKAGE

(TOP VIEW)

#### description

These 8-bit D-type transparent latches feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

While latch-enable (LE) input is high, the  $\overline{\mathbb{Q}}$  outputs follow the complements of the data (D) inputs. When LE is taken low, the  $\overline{\mathbb{Q}}$  outputs are latched at the inverses of the levels set up at the D inputs. The SN74ALS533A and SN74AS533A are functionally equivalent to the SN74ALS373A and SN74AS373, except for having inverted outputs.

A buffered output-enable (OE) input places the eight outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without interface or pullup components.

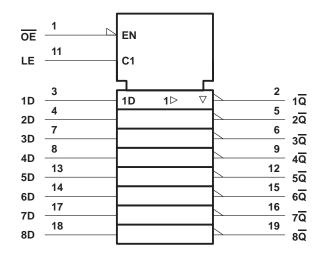
OE does not affect the internal operations of the latches. Old data can be retained or new data can be entered while the outputs are off.

The SN74ALS533A and SN74AS533A are characterized for operation from 0°C to 70°C.

## FUNCTION TABLE (each latch)

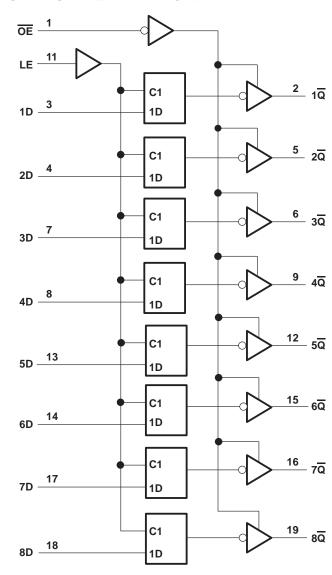
	INPUTS	OUTPUT	
OE	LE	D	Q
L	Н	Н	L
L	Н	L	Н
L	L	Χ	$\overline{Q}_0$
Н	Χ	Χ	Z

#### logic symbol†



<sup>&</sup>lt;sup>†</sup>This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

#### logic diagram (positive logic)



### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage, V <sub>CC</sub>	7 V
Input voltage, V <sub>I</sub>	7 V
Voltage applied to a disabled 3-state output	
Operating free-air temperature range, T <sub>A</sub> : SN74ALS533A	0°C to 70°C
Storage temperature range	-65°C to 150°C

<sup>‡</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

#### recommended operating conditions

		SN74ALS533A			UNIT
		MIN	NOM	MAX	UNII
VCC	Supply voltage	4.5	5	5.5	V
VIH	High-level input voltage	2			V
VIL	Low-level input voltage			0.8	V
IOH	High-level output current			-2.6	mA
loL	Low-level output current			24	mA
t <sub>W</sub>	Pulse duration, LE high	15			ns
t <sub>su</sub>	Setup time, data before LE↓	15			ns
t <sub>h</sub>	Hold time, data after LE↓	7			ns
TA	Operating free-air temperature	0		70	°C

#### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONF	TEST CONDITIONS				
PARAMETER	TEST CONL	MIN	TYP†	MAX	UNIT	
VIK	$V_{CC} = 4.5 V$ ,	$I_{I} = -18 \text{ mA}$			-1.5	V
Voн	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -0.4 \text{ mA}$	V <sub>CC</sub> -2			V
VОН	$V_{CC} = 4.5 V$ ,	$I_{OH} = -2.6 \text{ mA}$	2.4	3.2		
Ver	V <sub>CC</sub> = 4.5 V	I <sub>OL</sub> = 12 mA		0.25	0.4	V
VoL	∨CC = 4.5 V	I <sub>OL</sub> = 24 mA		0.35	0.5	V
lozн	$V_{CC} = 5.5 V,$	V <sub>O</sub> = 2.7 V			20	μΑ
lozL	$V_{CC} = 5.5 V,$	V <sub>O</sub> = 0.4 V			-20	μΑ
lj	$V_{CC} = 5.5 V,$	V <sub>I</sub> = 7 V			0.1	mA
liн	$V_{CC} = 5.5 V,$	V <sub>I</sub> = 2.7 V			20	μΑ
I <sub>IL</sub>	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 0.4 V			-0.1	mA
IO <sup>‡</sup>	V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 2.25 V	-30		-112	mA
		Outputs high		10	17	
ICC	$V_{CC} = 5.5 V$	Outputs low		17	26	mA
		Outputs disabled		18.5	28	

<sup>†</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .



<sup>&</sup>lt;sup>‡</sup> The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, los.

## SN74ALS533A, SN74AS533A OCTAL D-TYPE TRANSPARENT LATCHES WITH 3-STATE OUTPUTS

SDAS270 - DECEMBER 1994

#### switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4.5$ $C_{L} = 50 \text{ pF}$ $R1 = 500 \Omega$ $R2 = 500 \Omega$ $T_{A} = \text{MIN to}$ $SN74AL$	, , , , , , , , , , , , , , , , , , ,	UNIT	
			MIN	MAX		
<sup>t</sup> PLH	D	Q	4	19	ns	
<sup>t</sup> PHL	נ	g	4	13	110	
t <sub>PLH</sub>	LE	A G	5	23	ns	
<sup>t</sup> PHL	LL	Any Q	4	18	115	
<sup>t</sup> PZH		A <del>G</del>	1	17		
tPZL	ŌĒ	Any Q	4	18	ns	
t <sub>PHZ</sub>	ŌĒ	Any Q	2	10		
<sup>t</sup> PLZ	)E	Ally Q	2	16	ns	

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage, V <sub>CC</sub>	7 V
Input voltage, V <sub>I</sub>	$\dots \dots \dots \ 7 \ V$
Voltage applied to a disabled 3-state output	
Operating free-air temperature range, T <sub>A</sub> : SN74AS533A	$\dots$ 0°C to 70°C
Storage temperature range	-65°C to 150°C

<sup>‡</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

#### recommended operating conditions

		SN	SN74AS533A		UNIT
		MIN	NOM	MAX	UNII
Vcc	Supply voltage	4.5	5	5.5	V
VIH	High-level input voltage	2			V
V <sub>IL</sub>	Low-level input voltage			0.8	V
ІОН	High-level output current			-15	mA
loL	Low-level output current			48	mA
t <sub>W</sub>	Pulse duration, LE high	2			ns
t <sub>su</sub>	Setup time, data before LE↓	2			ns
th	Hold time, data after LE↓	3			ns
TA	Operating free-air temperature	0		70	°C

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST COND	SN	SN74AS533A			
PARAMETER	TEST CONL	THONS	MIN	TYP†	MAX	UNIT
VIK	$V_{CC} = 4.5 V,$	$I_{I} = -18 \text{ mA}$			-1.5	V
Van	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -2 \text{ mA}$	V <sub>CC</sub> -2			V
Voн	$V_{CC} = 4.5 V,$	$I_{OH} = -15 \text{ mA}$	2.4	3.3		V
V <sub>OL</sub>	$V_{CC} = 4.5 V,$	$I_{OL} = 48 \text{ mA}$		0.34	0.5	V
IOZH	$V_{CC} = 5.5 V,$	V <sub>O</sub> = 2.7 V			50	μΑ
lozL	$V_{CC} = 5.5 V,$	V <sub>O</sub> = 0.4 V			-50	μΑ
II	$V_{CC} = 5.5 V,$	V <sub>I</sub> = 7 V			0.1	mA
lін	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 2.7 V			20	μΑ
I <sub>IL</sub>	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 0.4 V		-0.02	-0.5	mA
1 <sub>O</sub> ‡	$V_{CC} = 5.5 V,$	V <sub>O</sub> = 2.25 V	-30		-112	mA
		Outputs high		62	100	
Icc	$V_{CC} = 5.5 V$	Outputs low		64	100	mA
		Outputs disabled		71	110	

<sup>†</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

#### switching characteristics (see Figure 1)

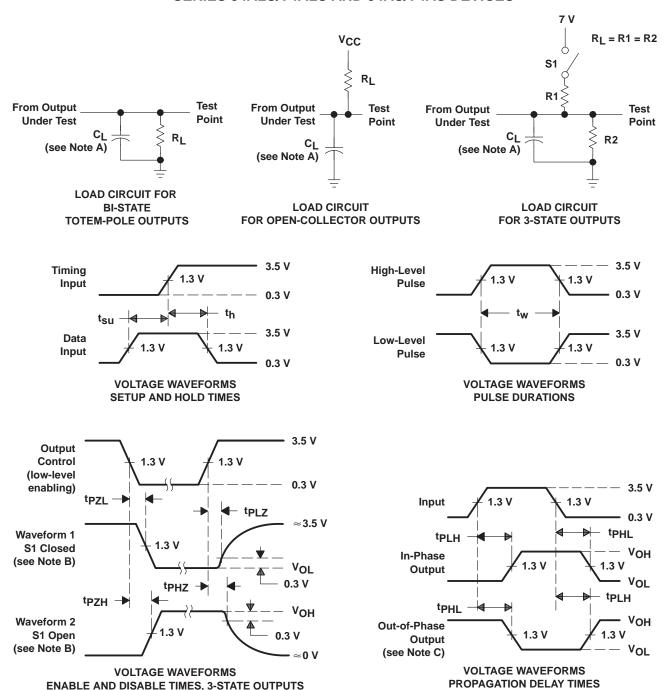
PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC}$ = 4.5 $^{\circ}$ $C_L$ = 50 pF R1 = 500 $\Omega$ R2 = 500 $\Omega$ $T_A$ = MIN to SN74A	; e, o MAX§	UNIT	
			MIN	MAX	1	
<sup>t</sup> PLH	D	Q	4	7.5	ns	
<sup>t</sup> PHL	ט	α	4	7	115	
<sup>t</sup> PLH	LE	A <del>-</del>	5	9		
<sup>t</sup> PHL	LE	Any Q	4	8	ns	
<sup>t</sup> PZH	<del></del>	. =	2	6.5		
tPZL	ŌĒ	Any Q	4	9.5	ns	
<sup>t</sup> PHZ	ŌĒ	Any 0	2	6.5		
tPLZ	)E	Any $\overline{Q}$	3	7	ns	

<sup>§</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



<sup>‡</sup> The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.

#### PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- D. All input pulses have the following characteristics: PRR  $\leq$  1 MHz,  $t_f = t_f = 2$  ns, duty cycle = 50%.
- E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms







31-Aug-2014

#### **PACKAGING INFORMATION**

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74ALS533ADW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS533A	Samples
SN74ALS533ADWR	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI	0 to 70		
SN74ALS533ADWRE4	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI	0 to 70		
SN74ALS533ADWRG4	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI	0 to 70		
SN74ALS533AN	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS533AN	Samples
SN74ALS533ANSR	ACTIVE	so	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS533A	Samples
SN74AS533ADW	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI	0 to 70	AS533A	
SN74AS533AN	OBSOLETE	PDIP	N	20	·	TBD	Call TI	Call TI	0 to 70	SN74AS533AN	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

<sup>(5)</sup> Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.



#### PACKAGE OPTION ADDENDUM

31-Aug-2014

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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## PACKAGE MATERIALS INFORMATION

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#### TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS533ANSR	SO	NS	20	2000	330.0	24.4	9.0	13.0	2.4	12.0	24.0	Q1

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#### \*All dimensions are nominal

Ī	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
	SN74ALS533ANSR	SO	NS	20	2000	367.0	367.0	45.0

## N (R-PDIP-T\*\*)

## PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.





SOIC



#### NOTES:

- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
- 5. Reference JEDEC registration MS-013.



SOIC



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOIC



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



#### **MECHANICAL DATA**

## NS (R-PDSO-G\*\*)

## 14-PINS SHOWN

#### PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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